# A Novel Very Low Voltage Topology to implement MCML XOR Gates

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Abstract—A new very low-voltage topology to implement MOS current mode logic (MCML) XOR gates is proposed in this paper. Instead of stacking several level of transistors to implement a two inputs XOR gate, a p-type differential pair is used to steer the current in n-type differential pairs through current mirrors. The proposed topology allows to reduce the minimum supply voltage of MCML XOR gates while guaranteeing a fully current mode behavior as in the conventional XOR gate. The proposed topology has been compared against the conventional and triple tail MCML XOR gates. Simulation results referring to a 40nm CMOS technology for  $V_{DD}=1V$  confirm that the XOR gate presented in this work exhibits a lower propagation delay than the previously published low voltage MCML XOR gate. Furthermore both theoretical analysis and simulation results in a 40nm process show that the proposed topology is able to work with a  $V_{DD}$  as low as 0.65V whereas state of the art topologies are not usable below 0.8V.

Keywords—MCML; low voltage; nanometer CMOS; current mode; XOR Gate.

## I. INTRODUCTION

High-speed digital communications and chip-to-chip interconnections are becoming more and more popular in the nanometer CMOS era. These applications require high performance logics suitable to be implemented with CMOS processes and able to guarantee high operating frequencies and low power consumption. Optical communications as well as, very high sampling frequency ADCs demand the use of logic styles able to operate at tens of Gb/s: these speeds cannot currently be achieved using the conventional CMOS logic style [1-3].

Mixed-signal integrated circuits have nowadays become pervasive due to the continuously increasing demand of systems on chip integrating digital and analog functions with more and more stringent specification requirements. The conventional CMOS logic style exhibits a large switching noise that lowers the performance of the analog building blocks and therefore it cannot be used on the same substrate with very high-resolution analog circuits [4-5]. MOS current mode logic (MCML) in contrast to the standard CMOS logic provides higher speed, better power efficiency at high frequencies, lower switching noise and lower sensitivity to process variations [6].

The exclusive-OR (XOR) gate is a key component to build high speed digital circuits such as comparators, adders, multipliers, test pattern generators etc. [7-10].

The most challenging drawback in the use of nanometer CMOS processes is the very low supply voltage available,

(which is usually less than 1V). This constraint on the supply voltage does not allow stacking several levels of transistors in a MCML gate, so that the traditional MCML XOR gate is not usable in practice anymore as will be pointed out in the next sections of this paper.

Low voltage CML topologies based on the triple tail cell concept have been introduced in [8] and analyzed in [9] referring to bipolar technologies. Recently, a new low-voltage MCML XOR gate topology has been proposed in [10]. It exploits the triple-tail cell concept, provides differential signaling and does not need any additional circuitry when compared against previous low voltage topologies. A MCML triple tail XOR gate topology exploiting multi-threshold CMOS processes has been introduced in [11]. Exploiting transistors with different threshold voltages, level shifters are not required, and supply voltage can be reduced [11].

In this work we present a novel low voltage MCML XOR gate topology in which the high performance of p-type MOS transistors in nanometer technologies is exploited to develop very low voltage logic gates by using a "folded" approach instead of the conventional "stacking" approach. A similar approach has been adopted in [12] for the implementation of low voltage D-Latches. In *Section II* we review the conventional MCML XOR gate and the triple tail XOR gate and compute the minimum supply voltage of the two circuits from a theoretical perspective. In Section III we introduce the proposed MCML XOR gate topology showing its advantages in terms of minimum supply voltage. Simulation results and comparisons are shown in Section IV. Conclusions are finally reported in section V.

# II. Review of MCML XOR Gate Topologies

### A. Conventional MCML XOR Gate

The circuit schematic of the conventional MCML XOR gate is depicted in Fig. 1. The transistor  $M_1$  implements the bias current source of  $I_{SS}$  value. MOS devices  $M_2$  to  $M_7$  implement the conditional pulldown network, whereas the active load is implemented through p-type transistors  $M_8$  and  $M_9$ . The upper level and lower level differential couples are driven by differential inputs A and B respectively. When input B is low,  $M_2$  is off, the tail current  $I_{SS}$  flows through  $M_3$  and is steered either to  $M_6$  or  $M_7$  according to the differential input A. The tail current  $I_{SS}$  is steered to the load transistors  $M_8$  and  $M_9$  to provide the differential output voltage [6].



Fig. 1 Conventional MCML XOR Gate

The output differential voltage swing  $V_{SWING}$  of the conventional MCML XOR gate can be written as:

$$V_{SWING} = 2 \cdot I_{SS} \cdot R_P \tag{1}$$

where  $R_P$  is the equivalent linear resistance of the p-type devices  $M_8$  and  $M_9$  computed as in [5], [10] and [13].

In order for this circuit to properly operate, all the NMOS transistors have to work in saturation and this condition set a limitation on the minimum supply voltage  $V_{DD}$ .

Denoting as  $V_{CMB}$  and  $V_{CMB}$  the common mode voltage of differential input A and B respectively, the following conditions have to be fulfilled in order to guarantee saturation operation for all NMOS devices in the XOR gate circuit in Fig. 1:

$$V_{DS1} = V_{CMB} - V_{GS2,3} > V_{DS1,sat}$$
(2)

$$V_{DS2,3} = V_{CMA} - V_{GS4-7} - (V_{CMB} - V_{GS2,3}) > V_{DS2,3,sat}$$
(3)

$$V_{DS4-7} = V_{DD} - \frac{V_{SWING}}{2} - (V_{CMA} - V_{GS4-7}) > V_{DS4-7,sat}$$
(4)

where  $V_{DS}$ ,  $V_{GS}$ , and  $V_{DS,sat}$  are the drain source, gate source and saturation drain source voltage of the different transistors in Fig. 1 respectively. From equations (2) and (3) it is evident that, setting  $V_{CMA} = V_{CMB}$  results in  $V_{DS2,3} = 0$ , if  $M_{2,3}$  and  $M_{4.7}$  are equally sized. In the past, MCML designers used source followers to lower the common mode voltage level  $V_{CMB}$  with respect to  $V_{CMA}$  thus allowing  $M_2$  and  $M_3$  to work in saturation [5], [6], [8], [11]. However, source follower stages are not power efficient and consume large silicon area footprint. Furthermore by using a source follower (implemented trough a common drain transistor  $M_{10}$ ) the implemented voltage shift is equal to  $V_{GS10}$ .

By using these assumptions the minimum supply voltage can be computed from (1) as follows:

$$V_{DS1} = V_{CMB} - V_{GS2,3} = V_{CMA} - V_{GS10} - V_{GS2,3}$$
(5)

Assuming that the differential signal A is the output of a conventional MCML inverter (differential pair) we can write:

$$V_{CMA} = V_{DD} - \frac{V_{SWING}}{4} \tag{6}$$

Finally, substituting (6) in (5) and using (2), we can express the minimum supply voltage for the conventional MCML XOR gate as follows:

$$V_{DD,min,conv} = \frac{V_{SWING}}{4} + V_{GS10} + V_{GS2,3} + V_{DS1,sat}$$
(7)





From (7), it is evident that the conventional MCML XOR gate is not suited to be used for  $V_{DD}$  in the range of 1V assuming typical device parameters for nanometer CMOS technologies.

## B. Triple Tail MCML XOR gate

The low-voltage triple tail XOR gate introduced in [10] is reported in Fig. 2. It is made up of two triple-tail cells ( $M_3$ ,  $M_4$ ,  $M_1$ ) and ( $M_5$ ,  $M_6$ ,  $M_2$ ) with two tail current sources of  $I_{SS}$  value. The MOS devices  $M_1$  and  $M_2$  are connected between the supply node and the common source node of differential pairs  $M_3$ – $M_4$ and  $M_5$ – $M_6$  respectively. When the differential input B is high,  $M_2$  is on and the differential pair  $M_5$ – $M_6$ .is off. In the same condition,  $M_1$  is off and the differential pair  $M_3$ – $M_4$  is on: the output voltage is generated according to the differential input A.

The minimum supply voltage,  $V_{DD,min,TT}$  for the triple tail XOR gate is computed by following the same approach followed for the conventional XOR gate as:

$$V_{DD,min,TT} = \frac{V_{SWING}}{4} + V_{GS3,4} + V_{DS7,sat}$$
(8)

where  $V_{DS}$ ,  $V_{GS}$ , and  $V_{DS,sat}$  are the drain source, gate source and saturation drain source voltage of the different transistors in Fig. 2 respectively.

It has to be pointed out that, the performances of the triple tail XOR gate strongly rely on the sizing of MOS devices  $M_1$  and  $M_2$  with respect to the other devices. Furthermore, the common-mode voltage and the voltage swing of inputs A and B have to be carefully chosen to provide proper operation. In particular, MOS devices  $M_1$  and  $M_2$  have to be sized much larger than the other transistors in order to keep the output swing high and guarantee a good noise margin [10].

According to [10] the output differential voltage swing for the triple tail XOR gate can be expressed as follows:

$$V_{SWING,TT} = 2R_P I_{SS} \frac{M}{1+M}.$$
(9)

where M is the ratio between the aspect ratios of  $M_{1,2}$  and  $M_{3-6}$ .

In order to keep the output swing high and guarantee a good noise margin, values of M in the range of 8-10 have to be chosen when adopting short channel MOS technologies. When M is set to be greater than 8 the input capacitance of  $M_1$  and  $M_2$  is very large and the gates (or buffers) driving  $M_1$  and  $M_2$  are heavily loaded: this results in a strong limitation of the speed performance of the triple tail XOR gate topology.



Fig. 3 Proposed Folded MCML XOR Gate

## III. Proposed MCML XOR gate topology

In this paragraph we introduce a novel, low voltage, MCML XOR gate. The proposed XOR gate exploits the idea of folding one level of the conventional XOR gate. The proposed topology is shown in Figure 3. When input B is low the P-channel differential couple  $M_1-M_2$  steers the current  $I_{SS}$  to the current mirror  $M_8-M_{10}$ , whereas, when input B is high  $I_{SS}$  is steered towards  $M_7-M_9$ . The differential pair made up of devices  $M_3-M_4$  is active when B is high, and the XOR gate generates the output according to the differential input A. When B is low only the differential couple  $M_5-M_6$  is active and the XOR gate generates the output according to not A.

### A. Minimum supply voltage

Denoting as  $V_{CMA}$  and  $V_{CMB}$  the common mode voltage of differential input *A* and *B* respectively, the following conditions have to be fulfilled in order to guarantee proper operation of the proposed XOR gate (i. e. all transistors from M<sub>1</sub> to M<sub>10</sub> working in saturation):

$$V_{DS9,10} = V_{CMA} - V_{GS3-6} > V_{DS9,10,sat}$$
(10)

$$V_{DS3,4} = V_{DD} - \frac{V_{SWING}}{2} - (V_{CMA} - V_{GS3-6}) > V_{DS3,4,sat}(11)$$

 $|V_{DS13}| = V_{DD} - (V_{CMB} - |V_{GS1,2}|) > |V_{DS13,sat}|$ (12)

Assuming that the differential signal A is the output of a conventional MCML inverter we can write  $V_{CMA} = V_{DD} - \frac{V_{SWING}}{4}$  as in (6). The differential input B in Figure 3 can be generated from a p-type MCML inverter (made up of a PMOS differential pair with NMOS load). In this cases  $V_{CMB}$  can be easily set to the optimum value which allows to minimize the supply voltage  $V_{DD}$ :

$$V_{CMB} = \frac{V_{SWING}}{4} \tag{13}$$

By using the expressions in (6) and (13) for  $V_{CMA}$  and  $V_{CMB}$  respectively in (10) and (12) the minimum supply voltage of the proposed folded XOR gate can be written as:

$$V_{DD,min,folded} = \frac{V_{SWING}}{4} + V_{GS3-6} + V_{DS9,10,sat}$$
(14).

# B. Threshold lowering for very low voltage XOR gates

Equation (14) can be rewritten in terms of the threshold voltages  $V_{TH}$  and overdrive voltages  $V_{OV} = V_{GS} - V_{TH}$  as follows:

$$V_{DD,min,folded} = \frac{V_{SWING}}{4} + V_{TH} + 2V_{OV}$$
(15)

Referring to a 40nm CMOS technology  $V_{TH}$  is typically in the range of 0.4V, whereas  $V_{OV}$  and  $\frac{V_{SWING}}{4}$  can be both set in the range of 0.1V, resulting in about 0.7V of minimum  $V_{DD}$ .

To further reduce the minimum supply voltage a threshold lowering technique based on moderate forward body bias can be exploited by using the following body connections for the circuit in Fig. 3: Body of  $M_1$  and  $M_2$  connected to ground; Body of  $M_7$ ,  $M_8$ ,  $M_9$  and  $M_{10}$  connected to the common source of  $M_1$  and  $M_2$ ; Body of  $M_3$ ,  $M_4$ ,  $M_5$  and  $M_6$  connected to *VDD*.

With this arrangement the  $V_{TH}$  can be reduced to about 0.3V and a minimum supply voltage in the range of 0.6V becomes feasible. It has to be noted that in this configuration all transistors are forward body biased by the same bulk source voltage  $V_{SB} = \frac{V_{SWING}}{4} + V_{TH} + V_{OV}$  which is about equal to 0.5V in a 40nm CMOS technology.

#### IV. DESIGN AND COMPARISONS

The triple tail XOR gate and the proposed XOR gate have been compared by means of transistor level simulations referring to a commercial 40nm CMOS technology within Cadence Virtuoso environment.

A supply voltage  $V_{DD} = 1$ V, an output swing  $V_{SWING} = 800$ mV and a reference bias current  $I_{SS} = 25\mu$ A have been assumed for the comparisons. All the comparisons have been carried out referring to the same power consumption for both circuits.

Bias settings and devices sizing for the reference tail current  $I_{SS}$  are shown in Table I. Values in Table I have then been scaled with the current according to [6] for  $I_{SS}$  ranging from 25 to 100µA.

It has to be noted that, for values of  $V_{SWING}$  lower than 800mV the triple tail XOR gate is not able to properly operate (M<sub>1</sub> and M<sub>2</sub> in Fig. 2 are not able to properly steer  $I_{SS}$  even for M=8), whereas the proposed folded XOR gate is able to work with  $V_{SWING}$  set to 400mV. The possibility to operate at lower  $V_{SWING}$  allows the proposed XOR gate to operate at a lower minimum supply voltage than the triple tail XOR gate.

The two XOR gate topologies have been simulated referring to two testbenches (TB1 and TB2) and two fan-out settings (FO1 and FO4). MCML inverter/buffer cells have been used as driving and load cells in all the simulations. In TB1 ideal voltage sources feed the differential A and B inputs of the gate under test, whereas in TB2 an MCML inverter/buffer cell, biased and sized at *I*<sub>SS</sub>, drives each one of the A and B inputs.

Simulation results for  $V_{DD}$ =1V and for the reference  $I_{SS}$  are summarized in Table I, and show that the proposed topology outperforms the triple tail one under testbench 2 conditions.

The propagation delay of the two compared XOR gates is reported in Figures 4 and 5.

Table I: Bias settings and devices sizing for the compared XOR gate.

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	Triple Tail XOR Gate	Proposed Folded
		XOR Gate
V <sub>DD</sub>	1V	1V
L	40nm	40nm
Reference I <sub>SS</sub>	25 μΑ	25 μΑ
$R_P$	16 KΩ	16 KΩ
W <sub>1,2</sub>	5.76 µm	0.72 µm
W <sub>3,4,5,6</sub>	0.72 µm	0.36 µm
W <sub>7,8,9,10</sub>	-	0.36 µm

Table II: comparisons in terms of propagation delay at  $I_{SS}=25\mu A$ 

	Triple Tail			Folded		
	CML	XOR	TOT	CML	XOR	TOT
	Buf (ps)	(ps)	(ps)	Buf (ps)	(ps)	(ps)
TB1-FO1	-	27.2	27.2	-	32.7	32.7
TB1-FO4	-	49.2	49.2	-	39.9	39.9
TB2-FO1	58.8	27.2	86.0	14.1	32.7	46.8
TB2-FO4	61.3	49.2	110.5	14.1	39.9	54.0



Fig. 4 Propagation delay comparisons for testbench1, in FO1 and FO4 conditions and  $V_{DD}$ =1V.



Fig. 5 Propagation delay comparisons for testbench2, in FO1 and FO4 conditions and  $V_{DD}$ =1V.



Fig. 6 Propagation delay as a function of  $I_{\rm SS}$  for the proposed Folded XOR gate for  $V_{\rm DD}{=}0.65V,$  testbench1, FO1 and FO4.

Finally, the proposed topology has been tested with  $V_{DD}$  set at its minimum value of 0.65V and the propagation delay as a function of  $I_{SS}$  is shown in Figure 6.

#### V. CONCLUSION

In this paper we have introduced a novel low voltage topology to implement MCML XOR gates. The proposed XOR gate and the low voltage triple tail XOR gate have been compared referring to a 40nm CMOS process. Simulation results for  $V_{DD} = 1$ V have demonstrated that the proposed topology allows a speed improvement of about 50% with respect to the triple tail one in the most common testbench conditions. Due to the capability to work with lower V<sub>SWING</sub>, and exploiting a threshold lowering technique, the proposed circuit has been able to work at the lowest minimum supply voltage. Simulation results have shown the capability to operate at  $V_{DD}$ =0.65V whereas the triple tail XOR gate is not able to properly work for  $V_{DD}$  lower than about 0.8V.

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